

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

James M. Derderian

Serial No.: 10/770,890

Filed: February 2, 2004

For: METHODS FOR FORMING ASSEMBLIES AND PACKAGES THAT INCLUDE STACKED SEMICONDUCTOR DEVICES SEPARATED A DISTANCE DEFINED BY ADHESIVE MATERIAL INTERPOSED THEREBETWEEN

Confirmation No.: 1094

Examiner: L. Thai

Group Art Unit: 2891

Attorney Docket No.: 2269-4817.3US
(01-0103.03/US)

Notice of Allowance Mailed:

September 14, 2007

VIA ELECTRONIC FILING

DECEMBER 12, 2007

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Amendments to the specification appear on page 3 of this paper;
A listing of the claims is set forth beginning on page 4 of this paper; and
Remarks start at page 11 of this paper.